

Title (en)  
EJECTABLE COMPONENT ASSEMBLIES IN ELECTRONIC DEVICES

Title (de)  
AUSSTOSSBARE KOMPONENTENGRUPPEN IN ELEKTRONISCHEN VORRICHTUNGEN

Title (fr)  
COMPOSANTS ÉJECTABLES DANS DES DISPOSITIFS ÉLECTRONIQUES

Publication  
**EP 2100488 B1 20160928 (EN)**

Application  
**EP 08713019 A 20080104**

Priority  
• US 2008000178 W 20080104  
• US 87880507 P 20070105  
• US 82403207 A 20070628

Abstract (en)  
[origin: US2008165508A1] Electronic devices are provided with ejectable component assemblies that can be substantially flush with the external surfaces of the housings of the devices, despite variations in their manufacture. The ejectable component assemblies may include connectors coupled to circuit boards of the devices, and trays that can be loaded with removable modules, inserted through openings in the housings of the devices, and into the connectors for functionally aligning the removable modules with the circuit boards. The ejectable component assemblies may also include ejectors coupled to the housings of the devices for ejecting the trays from the connectors and, thus, from the devices themselves.

IPC 8 full level  
**H05K 5/02** (2006.01)

CPC (source: EP US)  
**H04M 1/026** (2013.01 - EP US); **H05K 1/02** (2013.01 - US); **H05K 5/0295** (2013.01 - EP US); **H05K 7/1405** (2013.01 - US);  
**H05K 7/1427** (2013.01 - US); **G06K 13/08** (2013.01 - EP); **H04M 2250/14** (2013.01 - EP US)

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CN 201267077 Y 20090701; CN 201388349 Y 20100120; EP 2100488 A2 20090916; EP 2100488 B1 20160928; EP 2741593 A2 20140611;  
EP 2741593 A3 20140903; EP 2741593 B1 20170628; EP 3242541 A1 20171108; EP 3242541 B1 20190424; EP 3576504 A2 20191204;  
EP 3576504 A3 20200311; EP 3576504 B1 20210922; HK 1133361 A1 20100319; TW 200845868 A 20081116; TW 201240559 A 20121001;  
TW I377896 B 20121121; TW I533777 B 20160511; US 10277722 B2 20190430; US 11050865 B2 20210629; US 2011080699 A1 20110407;  
US 2012176753 A1 20120712; US 2014247567 A1 20140904; US 2017013098 A1 20170112; US 2019230202 A1 20190725;  
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EP 08713019 A 20080104; EP 13188605 A 20080104; EP 17172986 A 20080104; EP 19164687 A 20080104; HK 10100052 A 20100105;  
TW 101120788 A 20080104; TW 97100441 A 20080104; US 2008000178 W 20080104; US 201213429563 A 20120326;  
US 201414276610 A 20140513; US 201615275161 A 20160923; US 201916374611 A 20190403; US 96723410 A 20101214